OLED DISPLAY SPECIFICATION





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SPECIFICATION

Model No:

REX004864AWPP3N00000

CUSTOMER:

APPROVED BY	,							
PCB VERSION								
DATE								
FOR CUSTOMER USE	FOR CUSTOMER USE ONLY							
SALES BY	APPROVED BY	CHECKED BY	PREPARED BY					
FOR CUSTOMER USE		CHECKED BY	PREPARED BY					

Release DATE:

APPROVAL FOR SPECIFICATIONS ONLY

APPROVAL FOR SPECIFICATIONS AND SAMPLE



Revision History

VERSION	DATE	REVISED PAGE NO.	Note
0	2017/01/25		First release
A	2019/09/02		Modify Precautions in
			use of OLED
	0040/40/00		Modules
В	2019/12/02		Add Application
			recommendations &
			Initial code & Modify Reliability test
			Condition
С	2019/12/18		Modify Reliability Test
	2010/12/10		and measurement
			conditions &
			Inspection
			specification:" Accept
			no dense" modify to
			"ignore"& Precautions
D	2020/08/27		Modify Inspection
-	0000/11/10		specification
E	2020/11/18		Modify Storage
F	2024/02/25		Precautions
	2021/02/25		Modify Precautions in use of OLED
			Modules
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- 1. General Specification
- 2.Module Classification Information
- 3.Interface Pin Function
- 4.Contour Drawing & Block Diagram
- 5. Absolute Maximum Ratings
- **6.**Electrical Characteristics
- 7.Optical Characteristics
- 8.OLED Lifetime
- 9.Reliability
- 10.Inspection specification
- 11.Precautions in use of OLED Modules



1.General Specification

The Features is described as follow:

- Dot Matrix: 48 x 64 Dots
- Module dimension: 13.90 × 22.0 × 1.26mm
- Active Area: 10.54 ×14.70 mm
- Pixel Size: 0.198 × 0.208mm
- Pixel Pitch: 0.220 × 0.230 mm
- Display Mode: Passive Matrix
- Display Color: White
- Drive Duty: 1/64 Duty
- IC: SSD1306
- Interface:I2C
- Size:0.71 inch



2.Module Classification information

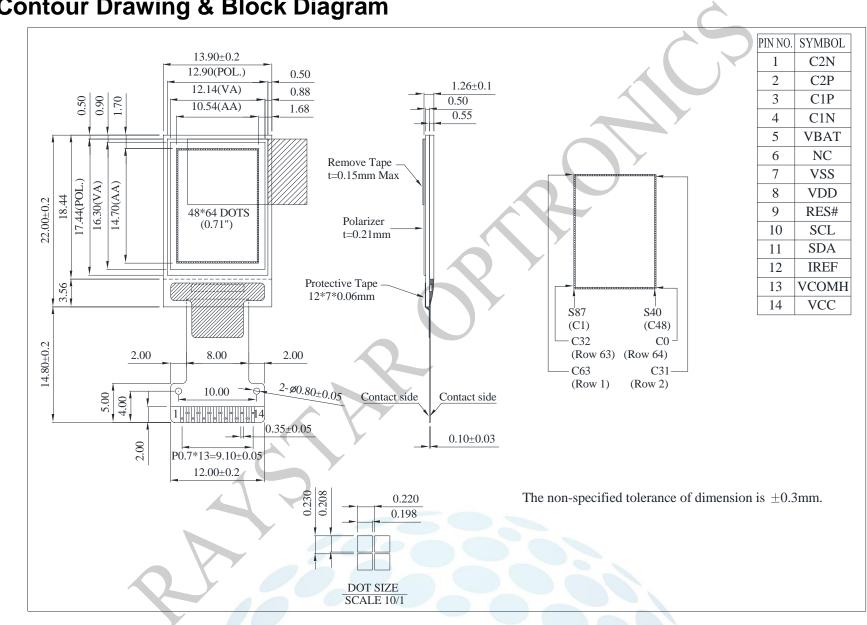
1	2	3	4	5	6	7	8	9	10	11	12	13	14
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L										I		Ċ	
1	Bran	d∶Ray	/star Op	tronics In	C.								
2	E : C	DLED											
3	Display Type X: COG H:					COB (COG - TAB		С					
4	Dot N	∕latrix ∶	48*64										
5	Serie	es											
6	Emit	ting Co	lor	B : Blue G : Gre	A : AmberR : RedB : BlueW : WhiteG : GreenY : YellowS : Sky BlueX : Dual Color				C :	C : Full Color			
7	Pola	rizer		P∶With A∶Anti				out Pol	arizer				
8	Disp	ay Mo	ode	P : Pas				ive Ma	atrix				
9	Drive	er Volta	ge	3:3.0~		,		-					
10	Touc	h Pane		N : With		uch pa	inel; T:	With t	ouch p	anel			
11	Prod	oduct type 0 : Standard 1 : Daylight Readable 2 : Transparent OLED (TOLED) 3 : Flexible OLED (FOLED) 4 : OLED Lighting							100				
12		ection C	Grade	0 : Standard 2 : B grade C : Automotive grade Y : Consumer grade						6			
13	Optic			0 : Defa				H : Ho	t bar F	PC; D	: Dem	o Kit	
14	Seria	al No.		Serial n	umber	(00~ZZ	<u>(</u>)			10	20	00	



3.Interface Pin Function

No.	Symbol	Function
1	C2N	Desitive Terminal of the Elving Inverting Conseitor Magative Terminal of the
2	C2P	Positive Terminal of the Flying Inverting Capacitor Negative Terminal of the
3	C1P	<i>Flying Boost Capacitor</i> The charge-pump capacitors are required between the terminals. They must be floated when the converter is not used.
4	C1N	the terminals. They must be hoated when the converter is not used.
5	VBAT	Power Supply for DC/DC Converter Circuit This is the power supply pin for the internal buffer of the DC/DC voltage converter. It must be connected to external source when the converter is used. It should be connected to VDD when the converter is not used.
6	NC	No connection.
7	VSS	Ground of Logic Circuit This is a ground pin. It acts as a reference for the logic pins. It must be connected to external ground.
8	VDD	Power Supply for Logic
		This is a voltage supply pin. It must be connected to external source.
9		Power Reset for Controller and Driver This pin is reset signal input. When the pin is low, initialization of the chip is executed.
10		Host Data Input/Output Bus
11	SDA	When serial mode is selected, D1 will be the serial data input SDIN and D0 will be the serial clock input SCLK. When I2C mode is selected, D2 & D1 should be tired together and serve as SDAout & SDAin in application and D0 is the serial clock input SCL.
12	IREF	This is segment output current reference pin. When external IREF is used, a resistor should be connected between this pin and Vss to maintain the IREF current at a maximum of 30uA. When internal IREF is used, this pin should be kept NC
13		Voltage Output High Level for COM Signal This pin is the input pin for the voltage output high level for COM signals. A capacitor should be connected between this pin and VSS.
14	VCC	Power Supply for OEL Panel This is the most positive voltage supply pin of the chip. A stabilization capacitor should be connected between this pin and VSS when the converter is used. It must be connected to external source when the converter is not used.





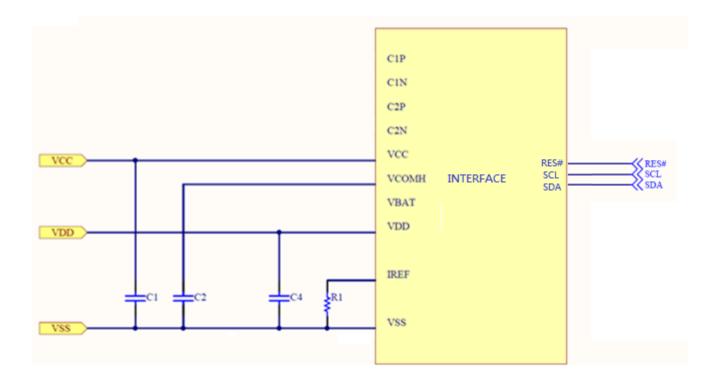
4.Contour Drawing & Block Diagram

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4.1 Application recommendations

External VCC Solution



Recommended components :

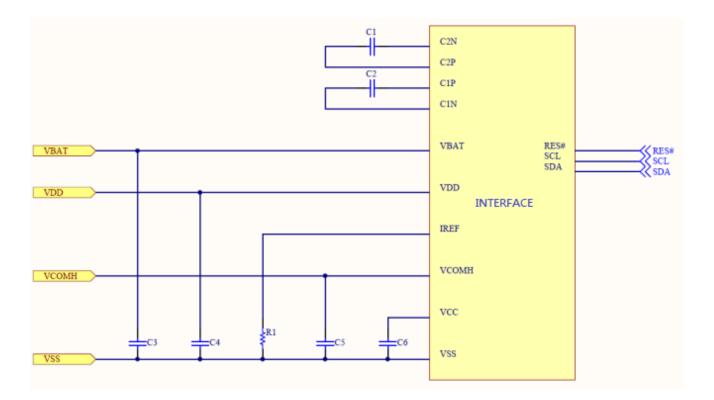
C1, C2 \colon 2.2uF

C4: 1.0 μ F

Voltage at IREF = VCC – 3V. For VCC = 7.5V, IREF = 30uA: R1 = (Voltage at IREF - VSS) / IREF = (7.5-3) / 30u = 150K ohm



Built-in DC-DC Solution



Recommended components :

C5, C6:2.2uF

C1, C2,C3, C4 : 1.0uF

Voltage at IREF = VCC - 3V. For VCC = 7.5V, IREF = 30uA: R1 = (Voltage at IREF - VSS) / IREF = (7.5-3) / 30u= 150K ohm



5.Absolute Maximum Ratings

Parameter	Symbol	Min	Мах	Unit	Notes
Supply Voltage for Logic	VDD	0	4.0	V	1,2
Supply Voltage for Display	VCC	0	15.0	V	1,2
Operating Temperature	TOP	-40	+80	°C	
Storage Temperature	TSTG	-40	+85	°C	_

Note 1: All the above voltages are on the basis of "VSS = 0V".

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section 6 "Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate



6.Electrical Characteristics

6.1 DC Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage for Logic	VDD	—	2.8	3.0	3.3	ζ
Supply Voltage for Display	VCC	—	7.0	7.5	8.0	V
Input High Volt.	VIH	—	0.8×VDD	T	VDD	V
Input Low Volt.	VIL	—	0		0.2×VDD	V
Output High Volt.	VOH	_	0.9×VDD		VDD	V
Output Low Volt.	VOL	-	0	_	0.1×VDD	V
50% Check Board operating Current	ICC	VCC=7.5V	×	15.0	25.0	mA

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}

6.2 Initial code

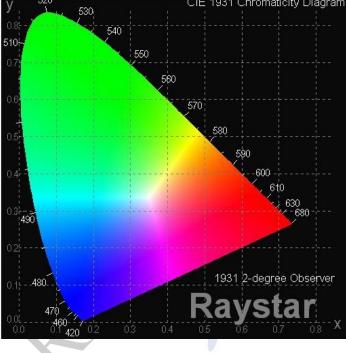
void initial_SSD1306(void){

Write_command(0xAE);	//Display Off
Write_command(0xD5); Write_command(0x80);	//SET DISPLAY CLOCK //105HZ
Write_command(0xA8); Write_command(0X3F);	//Select Multiplex Ratio //Default => 0~0x3F (1/64 Duty)
Write_command(0xD3); Write_command(0x00);	//Setting Display Offset //00H Reset, set common start
Write_command(0x40);	//Set Display Start Line
Write_command(0x8D); Write_command(0x10);	// Set Charge Pump // Disable Charge Pump
Write_command(0xA0);	//Set Segment Re-Map Default //0xA0 (0x00) => column Address 0 mapped to 127 //0xA1 (0x01) => Column Address 127 mapped to 0
Write_command(0xC0);	//Set COM Output Scan Direction
Write_command(0xDA); Write_command(0x12);	//Set COM Hardware Configuration //Alternative COM Pin //(0x02)=> A4=0;Sequential COM pin
Write_command(0x81); Write_command(0xBF);	//Set Contrast Control
Write_command(0xD9); Write_command(0x22);	//Set Pre-Charge period
Write_command(0xDB); Write_command(0x30);	//Set Deselect Vcomh level
Write_command(0xA4);	//Entire Display ON
Write_command(0xA6); Write_command(0xAF);	//Set Normal Display //Display ON
	<pre>Write_command(0xD5); Write_command(0xA8); Write_command(0xA8); Write_command(0xA8); Write_command(0xD3); Write_command(0x00); Write_command(0xA0); Write_command(0xA0); Write_command(0xA0); Write_command(0xC0); Write_command(0xDA); Write_command(0xA1); Write_command(0xBF); Write_command(0xBF); Write_command(0xD9); Write_command(0xD9); Write_command(0xD8); Write_command(0xA4); Write_command(0xA4);</pre>



7.Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
View Angle	(V)θ	—	160	—	-	deg
View Aligie	(H)φ	—	160	-		deg
Contrast Ratio	CR	Dark	2000:1	-	-	
Response Time	T rise	—	—	10	K	μs
	T fall	—	-	10	-	μs
Display with 50% che	ness	80	100	—	cd/m2	
CIEx(White)		(CIE1931)	0.26	0.28	0.30	-
CIEy(White)		(CIE1931)	0.30	0.32	0.34	
V 520	CIE 1931 Chrom	aticity Diagram				





8.OLED Lifetime

ITEM	Conditions	Min	Тур	Remark
Operating Life Time	Ta=25°C / Initial 50% check board brightness Typical Value	20,000 Hrs	-	Note

Notes:

- 1. Life time is defined the amount of time when the luminance has decayed to <50% of the initial value.
- 2. This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (*pdf*) for the product under normal use conditions.
- 3. Screen saving mode will extend OLED lifetime.



9.Reliability

Content of Reliability Test

Environmenta	ll Test	1	Annlinghia
Test Item	Content of Test	Test Condition	Applicable Standard
High Temperature storage	Endurance test applying the high storage temperature for a long time.	85°C 240hrs	- (
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-40°C 240hrs	
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	80°C 240hrs	1
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-40°C 240hrs	
High Temperature/ Humidity Storage	Endurance test applying the high temperature and high humidity storage for a long time.	60°C,90%RH 240hrs	
High Temperature/ Humidity Operation	Endurance test applying the high temperature and high humidity Operation for a long time.	60°C,90%RH 120hrs	
Temperature Cycle	Endurance test applying the low and high temperature cycle. -40°C 25°C 80°C 30min <u>5mjn 30min</u>	-40°C /80°C 30 cycles	
Mechanical Te	st		
Vibration test	Endurance test applying the vibration during transportation and using.	Frequency:10~55Hz amplitude:1.5mm Time:0.5hrs/axis Test axis:X,Y,Z	-0.
Others			
Static electricity test	Endurance test applying the electric stress to the finished product housing.	Air Discharge model ±4kv,10 times	_

*** Supply voltage for OLED system =Operating voltage at 25°C



Test and measurement conditions

- 1. All measurements shall not be started until the specimens attain to temperature stability. After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5°C; 55±15% RH.
- 2. All-pixels on/off exchange is used as operation test pattern.
- 3. The degradation of Polarizer are ignored for High Temperature storage, High Temperature/ Humidity Storage, Temperature Cycle

Evaluation criteria

- 1. The function test is OK.
- 2. No observable defects.
- 3. Luminance: > 50% of initial value.
- 4. Current consumption: within ± 50% of initial value.

APPENDIX:

RESIDUE IMAGE

Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.



10.Inspection specification

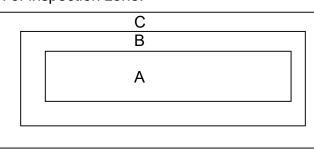
Inspection Standard:

MIL-STD-105E table normal inspection single sample level II.

Definition

1 Major defect : The defect that greatly affect the usability of product.

2 Minor defect : The other defects, such as cosmetic defects, etc. Definition of inspection zone:



Zone A: Active Area

Zone B: Viewing Area except Zone A

- Zone C: Outside Viewing Area
- Note: As a general rule, visual defects in Zone C are permissible, when it is no trouble of quality and assembly to customer's product.

Inspection Methods

- 1 The general inspection : Under fluorescent light illumination: 750~1500 Lux, about 30cm viewing distance, within 45° viewing angle, under 25±5°C.
- 2 The luminance and color coordinate inspection : By SR-3 or BM-7 or the equal equipments, in the dark room, under 25±5°C.

NO	Item	Criterion	AQL
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 OLED viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. 	0.65
02	Black or white spots on OLED (display only)	 2.1 White and black spots on display □0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm. 	2.5



NO	Item		Crite	rion			AQL		
	OLED black spots, white spots, contamin ation (non- display)	3.1 Round type : As following drawing $\Phi=(x + y) / 2$	SIZE $\Phi \le 0.10$ $0.10 < \Phi \le 0.2$ $0.20 < \Phi \le 0.2$ $0.25 < \Phi$		Acceptable QTY ignore 2 1 0	Zone A+ B, A+ B A+ B A+ B	2.5		
03		3.2 Line type : (As → L Length L=3.0	h Width W≦0.02		Acceptable Q TY ignore	Zone A+B	2.5		
		L≦3.(L≦2.:			2 As round type	A+B A+B			
			Y		503				
04	Polarizer bubbles /Dent	 4.1 If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction. 4.2 The polarizer d 	Size Φ $\Phi \leq 0.20$ $0.20 < \Phi \leq 0.50$ $0.50 < \Phi \leq 1.00$ $1.00 < \Phi$ Total Q TY ent follows this spece		$\begin{array}{c} \Phi \leq 0.20 \\ 0.20 < \Phi \leq 0.50 \\ 0.50 < \Phi \leq 1.00 \\ 1.00 < \Phi \end{array}$		cceptable Q TY ignore 3 2 0 3 ication.	Zone A+B A+B A+B A+B	2.5
05	Scratches	Follow NO.3 OLED) black spots, w	vhite sp	oots, contaminat	ion.			



NO	Item	Criterion	AQL
	Chipped glass	Symbols Define: x: Chip length k: Seal widthy: Chip width t: Glass thickness 	2.5
06		6.1.2 Corner crack: x z x z z : Chip thickness y : Chip width $z \leq 1/2t$ Not over viewing area $x \leq 1/8a$ $1/2t < z \leq 2t$ Not exceed $1/3k$ $x \leq 1/8a$ 0 If there are 2 or more chips, x is the total length of each chip.	2.5
	Glass crack	Symbols : x: Chip length k: Seal widthy: Chip width t: Glass thickness 	2.5
		10000	00

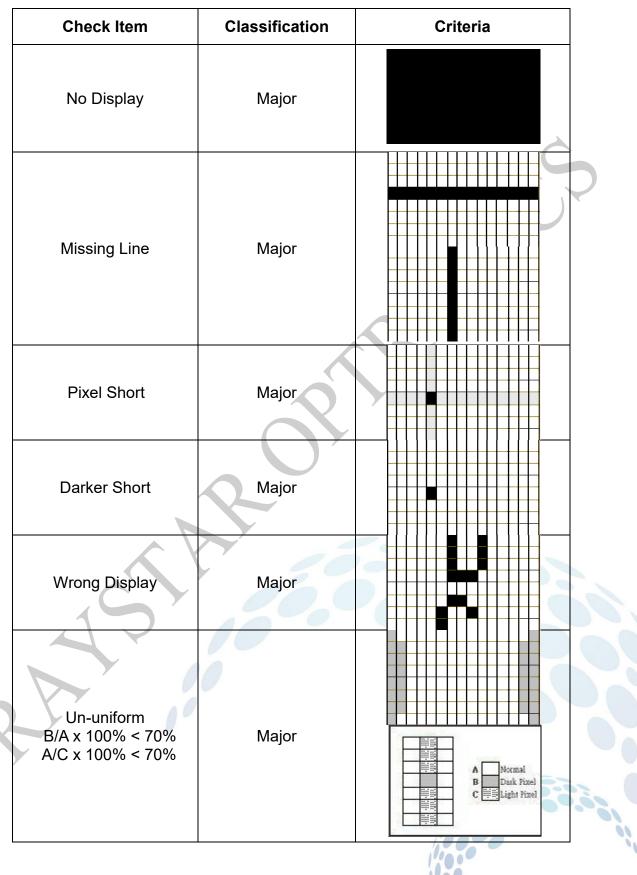


NO	Item	Criterion	AQL
06	Glass crack	6.2.2 Non-conductive portion: y y x y x y y x y	2.5
07	Cracked glass	The OLED with extensive crack is not acceptable.	2.5
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using OLED spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.	2.5 0.65



NO	Item	Criterion	AQL
10	PCB , COB	10.1 COB seal may not have pinholes larger than 0.2mm or contamination.	2.5
		10.2 COB seal surface may not have pinholes through to the IC.	2.5
		10.3 The height of the COB should not exceed the height	0.65
		indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than	2.5
		three places.	0.5
		10.5 No oxidation or contamination PCB terminals.	2.5
		10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts.	0.65
		10.7 The jumper on the PCB should conform to the product characteristic chart.	0.65
		10.8 If solder gets on bezel tab pads, OLED pad, zebra pad or screw hold pad, make sure it is smoothed down.	2.5
11	Soldering	11.1 No un-melted solder paste may be present on the PCB.	2.5
		11.2 No cold solder joints, missing solder connections, oxidation or icicle.	2.5
		11.3 No residue or solder balls on PCB.	2.5
		11.4 No short circuits in components on PCB.	0.65
	General appearance	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
12		12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever.	2.5
		12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.	2.5
		12.7 Sealant on top of the ITO circuit has not hardened.	2.5
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 OLED pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging specification sheet.	0.65
		12.11 Product dimension and structure must conform to product specification sheet.	0.65
			_
		Page 22 , Total 28 Pages	
		-	







11.Precautions in use of OLED Modules

Modules

- (1) Avoid applying excessive shocks to module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, change the components or modify its shape of OLED display module.
- (3) Don't disassemble the OLED display module.
- (4) Do not apply input signals while the logic power is off.
- (5) Don't operate it above the absolute maximum rating.
- (6) Don't drop, bend or twist OLED display module.
- (7) Soldering: only to the I/O terminals.
- (8) Hot-Bar FPC soldering condition: 280~350C, less than 5 seconds.
- (9) Raystar has the right to change the passive components (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.) and change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Raystar have the right to modify the version.)
- (10) Raystar has the right to upgrade or modify the product function.
- (11) For COG & COF structure OLED products, customers should reserve VCC (VPP) adjustment function or software update function when designing OLED supporting circuit. (The progress of OLED light-emitting materials will increase the conversion efficiency and the brightness. The brightness can be adjusted if necessary).

11.1. Handling Precautions

- (1) Since the display panel is being made of glass, do not apply mechanical impacts such as dropping from a high position.
- (2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
- (3) If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged. So, be careful not to apply pressure to these sections.
- (4) The polarizer covering the surface of the OLED display module is soft and easily scratched.
- (5) When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage by using following adhesion tape.

* Scotch Mending Tape No. 810 or an equivalent

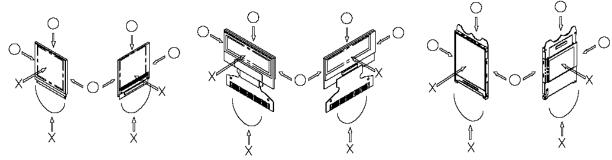
Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent such as ethyl alcohol, since the surface of the polarizer will become cloudy. Also, pay attention that the following liquid and solvent may spoil the polarizer:

- * Water
- * Ketone
- * Aromatic Solvents
- (6) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored for a long period of time, residue adhesive material of the protection film may remain on the surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5.
- (7) Do not touch the following sections whenever possible while handling the OLED display



modules.

- * Pins and electrodes
- * Pattern layouts such as the TCP & FPC
- (8) Hold OLED display module very carefully when placing OLED display module into the System housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.



- (9) Do not apply stress to the LSI chips and the surrounding molded sections.
- (10) Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity.
 - * Be sure to make human body grounding when handling OLED display modules.
 - * Be sure to ground tools to use or assembly such as soldering irons.

* To suppress generation of static electricity, avoid carrying out assembly work under dry environments.

* Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static electricity may be generated when exfoliating the protective film.

11.2. Storage Precautions

- (1) When storing OLED display modules, put them in static electricity preventive bags to avoid be directly exposed to sun or lights of fluorescent lamps. And, also, place in the temperature 25±5°C and Humidity below 65% RH.(We recommend you to store these modules in the packaged state when they were shipped from Raystar. At that time, be careful not to let water drops adhere to the packages or bags.)
- (2) When the OLED display module is being dewed or when it is placed under high temperature or high humidity environments, the electrodes may be corroded if electric current is applied. Please store it in clean environment.

11.3. Designing Precautions

- (1) The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, OLED display module may be damaged.
- (2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specification and to make the signal line cable as short as possible.
- (3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD / VCC). (Recommend value: 0.5A)
- (4) Pay sufficient attention to avoid occurrence of mutual noise interference with the nearby devices.

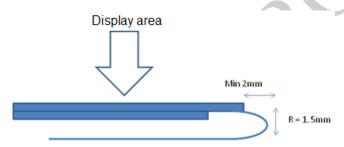




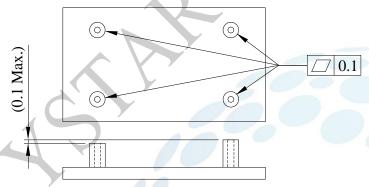
- (5) As for EMI, take necessary measures on the equipment side basically.
- (6) If the power supplied to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module.

* Connection (contact) to any other potential than the above may lead to rupture of the IC.

- (7) If this OLED driver is exposed to light, malfunctioning may occur and semiconductor elements may change their characteristics.
- (8) The internal status may be changed, if excessive external noise enters into the module. Therefore, it is necessary to take appropriate measures to suppress noise generation or to protect module from influences of noise on the system design.
- (9) We recommend you to make periodical refreshment of the operation statuses (re-setting of the commands and re-transference of the display data) to cope with catastrophic noise.
- (10) It's pretty common to use "Screen Saver" to extend the lifetime and Don't use the same image for long time in real application. When an OLED display module is operated for a long of time with fixed pattern, an afterimage or slight contrast deviation may occur.
- (11) The limitation of FPC and Film bending.



(12) The module should be fixed balanced into the housing, or the module may be twisted.



(13) Please heat up a little the tape sticking on the components when removing it; otherwise the components might be damaged.

11.4. Precautions when disposing of the OLED display modules

(1) Request the qualified companies to handle industrial wastes when disposing of the OLED display modules. Or, when burning them, be sure to observe the environmental and hygienic laws and regulations.





		Page: 1
	<u>le Sample</u>	Estimate Feedback Sheet
Module Number :		
1 · <u>Panel Specification</u> :		
1. Panel Type ∶	Pass	□NG ,
2. Numbers of Pixel :	Pass	□NG ,
3. View Area∶	Pass	□NG ,
4. Active Area ∶	Pass	□NG ,
5.Emitting Color :	Pass	□NG ,
6.Uniformity:	□Pass	□NG ,
7.Operating	Pass	□NG ,
Temperature :		y y
8.Storage	Pass	□NG ,
Temperature :		
9.Others :		
2 · Mechanical Specificat	1	
1. PCB Size :	□Pass	□NG ,
2.Frame Size :	□Pass	□NG ,
3.Materal of Frame :	□Pass	□NG ,
4.Connector Position :	□Pass	□NG ,
5.Fix Hole Position :	□Pass	□NG ,
6. Thickness of PCB :	□Pass	□NG ,
7. Height of Frame to	□Pass	□NG ,
PCB :		
8.Height of Module :	□Pass	□NG ,
9.Others :	□Pass	□NG ,
3 · <u>Relative Hole Size</u> :		
1.Pitch of Connector :	□Pass	□NG ,
2.Hole size of	□Pass	□NG ,
Connector :		
3.Mounting Hole size :	□Pass	□NG ,
4.Mounting Hole Type :	□Pass	□NG ,
5.Others :	□Pass	□NG ,
	·	Go to page 2 < <



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Module Number ∶ 4	ics of Modu	
1.Input Voltage :		□NG ,
2.Supply Current :		□NG ,
3.Driving Voltage for		□NG ,
OLED :		
4.Contrast for OLED :	□Pass	□NG ,
5.Negative Voltage	□Pass	□NG ,
Output :		
6.Interface Function :	□Pass	□NG ,
7.ESD test :	□Pass	□NG ,
8.Others : 5 \ <u>Summary</u> :	□Pass	□NG ,
15	R	
Sales signature : _	10	
Sales signature : _ Customer Signatur	e :	Date : / /